MICROWAVE POWER GAAS FET

PRELIMINARY

Features

- · Low intermodulation distortion
 - IM₃ = -45 dBc at Po = 35.0 dBm
- · High power
- P_{1dB} = 45.5 dBm at 5.9 to 6.4 GHz
 High efficiency
- - η_{add} = 37% at 5.9 to 6.4 GHz
- - $G_{1dB} = 8.0 dB$ at 5.9 to 6.4 GHz
- · Broadband internally matched
- · Hermetically sealed package

RF Performance Specifications ($T_a = 25^{\circ}C$)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Output Power at 1dB Compression Point	P _{1dB}	V _{DS} = 10V f = 5.9 ~ 6.4 GHz	dBm	45.0	45.5	_
Power Gain at 1dB Compression Point	G _{1dB}		dB	7.0	8.0	_
Drain Current	I _{DS}		Α	_	8.0	9.0
Power Added Efficiency	η_{add}		%	_	37	_
3rd Order Intermodulation Distortion	IM ₃	Note 1	dBc	-42	-45	_
Channel-Temperature Rise	ΔT_ch	V _{DS} x I _{DS} x R _{th (c-c)}	°C	-	1	100

Note 1: 2-tone Test Pout, Po = 35 dBm Single Carrier Level.

Electrical Characteristics (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	$V_{DS} = 3V$ $I_{DS} = 10.5A$	mS	_	6500	_
Pinch-off Voltage	V _{GSoff}	$V_{DS} = 3V$ $I_{DS} = 140 \text{ mA}$	V	-1.0	-2.5	-4.0
Saturated Drain Current	I _{DSS}	$V_{DS} = 3V$ $V_{GS} = 0V$	Α	_	20	26
Gate-Source Breakdown Voltage	V_{GSO}	I _{GS} = -420 μA	٧	-5	_	-
Thermal Resistance	R _{th (c-c)}	Channel to Case	°C/W	_	1.0	1.3

The information contained here is subject to change without notice.

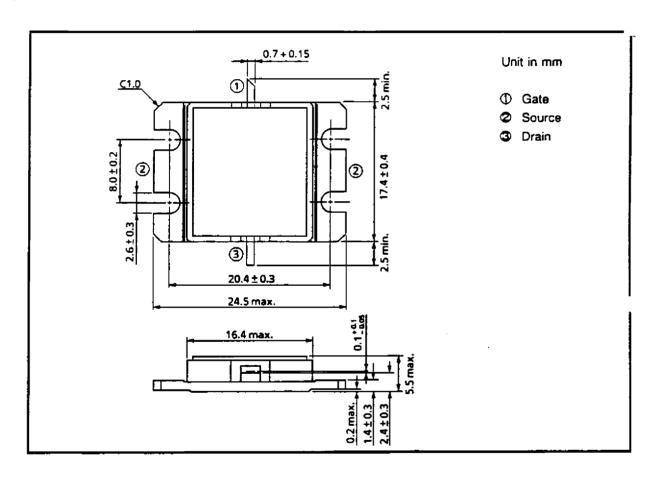
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Absolute Maximum Ratings ($T_a = 25^{\circ}C$)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V _{DS}	٧	15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _{DS}	Α	26
Total Power Dissipation (T _c = 25°C)	P_{T}	W	115
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	Ç	-65 ~ 175

Package Outline (2-16G1B)

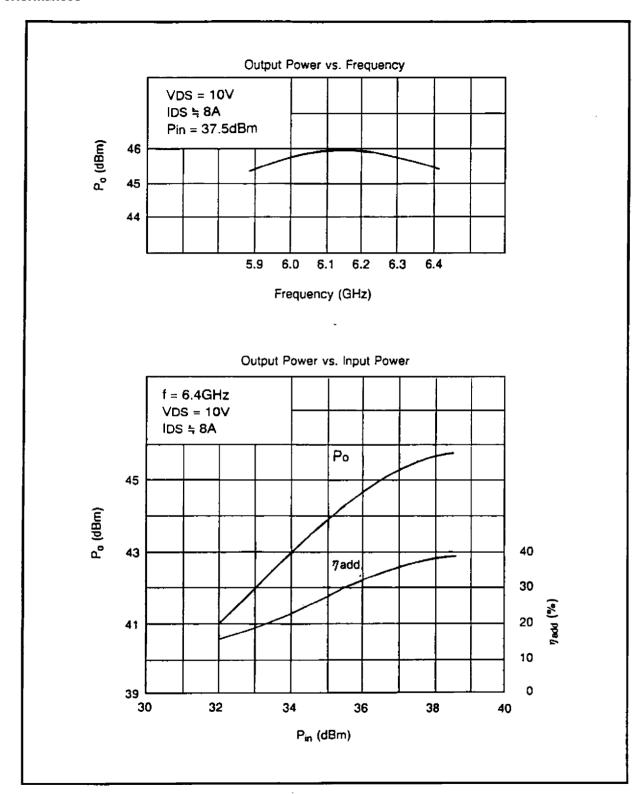


Handling Precautions for Packaged Type

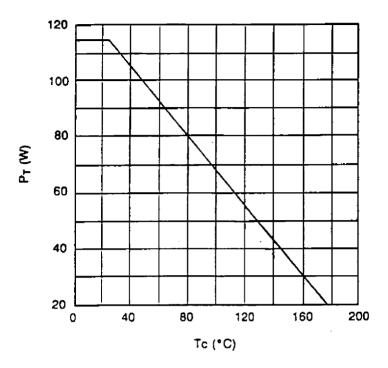
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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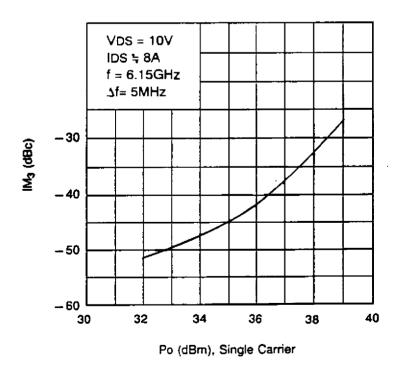
RF Performances



Power Dissipation vs. Case Temperature



IM₃ vs. Output Power Characteristics



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